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Richard S. Post, CEO
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For immediate release

NEXX Systems Announces Acquisition of All Wet Technologies, inc.

Wilmington, MA – April 23, 2003 – NEXX Systems today announced it has completed the acquisition of All Wet Technologies, Inc. (AWT). AWT has developed leading edge, low cost, high performance electro-deposition technology for metal and photoresist. Mr. Arthur Keigler, president of AWT, joins NEXX Systems as vice president of technology and board member.

"The AWT product line enhances the NEXX Systems' product offering, enabling NEXX to provide more complete solutions to their packaging challenges," stated Richard Post, chief executive officer of NEXX Systems. "Additionally, Mr. Keigler brings to the NEXX Systems' team a breadth of experience in wafer processing that will significantly contribute to our ability to meet the challenges and satisfy the demands of the advanced packaging market."

With the acquisition, NEXX Systems will offer two new product lines (in addition to its Nimbus PVD and Cirrus CVD systems):

- The **Stratus** systems for electro-deposition applications in gold and solder bumping, redistribution, and MEMS. The Stratus integrates the wafer quality and process advantages of vertical orientation with the economic advantages of parallel processing.
- The **Cirrostratus** systems for photoresist electro-deposition targeted at wafer bumping and MEMS-type thick film processes. The Cirrostratus offers the advantages of completely conformal coatings, elimination of waste, and faster processing times for very thick coatings.

"Combining AWT's wet process toolset with NEXX's dry process toolset provides a powerful opportunity to support customer needs in advanced packaging," stated Mr. Keigler. "Wafer level packaging is rapidly maturing past simple solder bump applications to include more complex structures, integrated passive components, and wafer-like processing of packaging substrates. The broad product line NEXX Systems can now offer will enable customers to quickly and cost effectively bring these processes into production."

NEXX Systems designs, develops, and manufactures technologically advanced solutions for the semiconductor advanced packaging, telecommunications, and optoelectronics markets. NEXX Systems' products provide established platforms specifically focused on flip chip advanced packaging, including wafer metallization, CVD and etch technologies. Additional information can be found at: www.nexxsystems.com.

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